

MICROFEATURE WORKPIECE SUBSTRATES HAVING THROUGH-SUBSTRATE VIAS, AND ASSOCIATED METHODS OF FORMATION

ABSTRACT OF THE DISCLOSURE

Microfeature workpiece substrates having through-substrate vias, and associated methods of formation are disclosed. A method in accordance with one embodiment for forming a support substrate for carrying microfeature dies includes exposing a support substrate to an electrolyte, with the support substrate having a first side with a first conductive layer, a second side opposite the first side with a second conductive layer, and a conductive path extending through the support substrate from the first conductive layer to the second conductive layer. The method can further include forming a bond pad at a bond site of the first conductive layer by disposing at least one conductive bond pad material at the bond site, wherein disposing the at least one conductive bond pad material can include passing an electrical current between the first and second conductive layers via the conductive path, while the substrate is exposed to the electrolyte.

Figure : 1A